Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: PNA 044 VQFN 7x7x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	72.55	(mg) Total	Mold Compound	% ot Total Weight	61.43
Silica, fused	60676-86-0	Mold Compound	55.287	65,294	552.870		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.979	3,519	29,794		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.979	3.519	29,794		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.184	0.218	1,843		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	33.636	39.724	336,358			Total	100.00	
Iron	7439-89-6	Lead Frame	0.051	0.060	506	39.81	(mg) Total	Lead Frame	% of Total Weight	33.71
Phosphorous	7723-14-0	Lead Frame	0.013	0.016	135		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.010	0.012	101		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.141	0.166	1.406		Phosphorous	7723-14-0	0.04	
Epoxy resin	68475-94-5	Die Attach	0.044	0.052	437		Zinc (Metal)	7440-66-6	0.03	
Copper(II) oxide	1317-38-0	Die Attach	0.006	0.007	57	Į.		Total	100.00	
Silicon	7440-21-3	Chip (Die)	1.750	2.067	17.500	0.22	(mg) Total	Die Attach	% of Total Weight	0.19
Gold	7440-57-5	Wire Bond	1.750	2.067	17,500	0.22	Silver	7440-22-4	74.00	0.19
Nickel	7440-02-0	Plating on external leads (pins)	1.079	1.274	10,791		Epoxy resin	68475-94-5	23.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.087	0.103	874		Copper(II) oxide	1317-38-0	3.00	
Gold	7440-53-5	Plating on external leads (pins)	0.007	0.004	35	ļ	Copper(II) Oxide	Total	100.00	
Guiu	1440-31-3	rialing on external leads (pins)	0.004	0.004				i otai		
		TOTAL C.	100 000	110 100	1 000 000	2.07	Total (man)	Chin (Dia)	0/ of Total Mainle	4 75
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